CYPRESS

64/256/512/1K/2K/4K/8K x 9 Synchronous FIFOs

Features

- **High-speed, low-power, First-In, First-Out (FIFO) memories**
- **64 x 9 (CY7C4421)**
- **256 x 9 (CY7C4201)**
- **512 x 9 (CY7C4211)**
- **1K x 9 (CY7C4221)**
- **2K x 9 (CY7C4231)**
- **4K x 9 (CY7C4241)**
- **8K x 9 (CY7C4251)**
- **High-speed 100-MHz operation (10 ns read/write cycle time)**
- **Low power (I_{CC} = 35 mA)**
- **Fully asynchronous and simultaneous read and write operation**
- **Empty, Full, and Programmable Almost Empty and Almost Full status flags**
- **TTL-compatible**
- **Expandable in width**
- **Output Enable ($\overline{OE}$) pin**
- **Independant read and write enable pins**
- **Center power and ground pins for reduced noise**
- **Width Expansion Capability**
- **Space saving 7 mm x 7 mm 32-pin TQFP**
- **32-pin PLCC**
- **Pin compatible and functionally equivalent to IDT72421, 72201, 72211, 72221, 72231, and 72241**
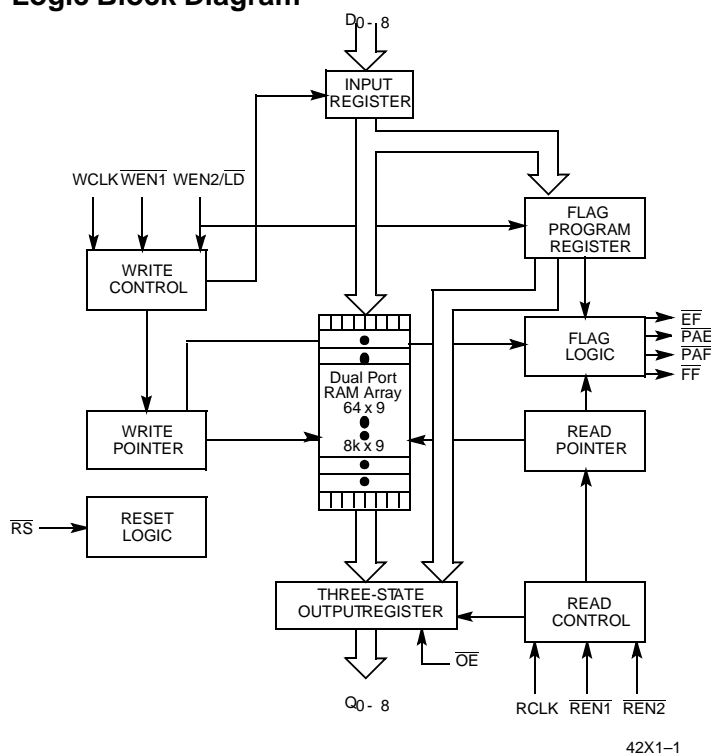
Functional Description

The CY7C42X1 are high-speed, low-power, First-In First-Out (FIFO) memories with clocked read and write interfaces. All are 9 bits wide. The CY7C42X1 are pin-compatible to IDT722X1. Programmable features include Almost Full/Almost Empty flags. These FIFOs provide solutions for a wide variety of data buffering needs, including high-speed data acquisition, multiprocessor interfaces, and communications buffering.

These FIFOs have 9-bit input and output ports that are controlled by separate clock and enable signals. The input port is controlled by a free-running clock (WCLK) and two write-enable pins ($\overline{WEN1}$, WEN2/$\overline{LD}$).

When $\overline{WEN1}$ is LOW and WEN2/$\overline{LD}$ is HIGH, data is written into the FIFO on the rising edge of the WCLK signal. While $\overline{WEN1}$, WEN2/$\overline{LD}$ is held active, data is continually written into the FIFO on each WCLK cycle. The output port is controlled in a similar manner by a free-running read clock (RCLK) and two read-enable pins ($\overline{REN1}$, $\overline{REN2}$). In addition, the CY7C42X1 has an output enable pin ($\overline{OE}$). The read (RCLK) and write (WCLK) clocks may be tied together for single-clock operation or the two clocks may be run independently for asynchronous read/write applications. Clock frequencies up to 100 MHz are achievable.

Depth expansion is possible using one enable input for system control, while the other enable is controlled by expansion logic to direct the flow of data.

Logic Block Diagram

42X1–1

Pin Configuration

PLCC Top View

42X1–2

TQFP Top View

42X1–3
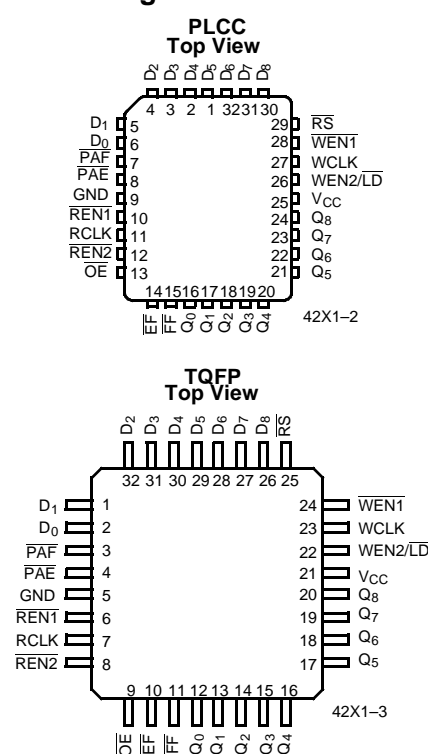
Functional Description (continued)

The CY7C42X1 provides four status pins: Empty, Full, Almost Empty, Almost Full. The Almost Empty/Almost Full flags are programmable to single word granularity. The programmable flags default to Empty – 7 and Full – 7.

The flags are synchronous, i.e., they change state relative to either the read clock (RCLK) or the write clock (WCLK). When entering or exiting the Empty and Almost Empty states, the flags are updated exclusively by the RCLK. The flags denoting Almost Full, and Full states are updated exclusively by WCLK. The synchronous flag architecture guarantees that the flags maintain their status for at least one cycle

All configurations are fabricated using an advanced 0.65μ N-Well CMOS technology. Input ESD protection is greater than 2001V, and latch-up is prevented by the use of guard rings.

Selection Guide

	CY7C42X1-10	CY7C42X1-15	CY7C42X1-25
Maximum Frequency (MHz)	100	66.7	40
Maximum Access Time (ns)	8	10	15
Minimum Cycle Time (ns)	10	15	25
Minimum Data or Enable Set-Up (ns)	3	4	6
Minimum Data or Enable Hold (ns)	0.5	1	1
Maximum Flag Delay (ns)	8	10	15
Active Power Supply Current (I_{CC1}) Commercial	35	35	35
Active Power Supply Current (I_{CC1}) Industrial	40	40	40

	CY7C4421	CY7C4201	CY7C4211	CY7C4221	CY7C4231	CY7C4241	CY7C4251
Density	64 x 9	256 x 9	512 x 9	1K x 9	2K x 9	4K x 9	8K x 9

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ....–65°C to +150°C

Ambient Temperature with
Power Applied ....–55°C to +125°C

Supply Voltage to Ground Potential .... –0.5V to +7.0V

DC Voltage Applied to Outputs
in High Z State .... –0.5V to +7.0V

DC Input Voltage.. –3.0V to +7.0V

Note:
1. T_A is the "instant on" case temperature.

Output Current into Outputs (LOW)............................ 20 mA

Static Discharge Voltage .... >2001V
(per MIL-STD-883, Method 3015)

Latch-Up Current.. >200 mA

Operating Range

Range	Ambient Temperature	V_{CC}
Commercial	0°C to +70°C	5V ± 10%
Industrial[1]	–40°C to +85°C	5V ± 10%

Pin Definitions

Signal Name	Description	I/O	Description
D_{0-8}	Data Inputs	I	Data Inputs for 9-bit bus
Q_{0-8}	Data Outputs	O	Data Outputs for 9-bit bus
$\overline{\text{WEN1}}$	Write Enable 1	I	The only write enable when device is configured to have programmable flags. Data is written on a LOW-to-HIGH transition of WCLK when $\overline{\text{WEN1}}$ is asserted and $\overline{\text{FF}}$ is HIGH. If the FIFO is configured to have two write enables, data is written on a LOW-to-HIGH transition of WCLK when $\overline{\text{WEN1}}$ is LOW and WEN2/$\overline{\text{LD}}$ and $\overline{\text{FF}}$ are HIGH.
WEN2/$\overline{\text{LD}}$ Dual Mode Pin	Write Enable 2	I	If HIGH at reset, this pin operates as a second write enable. If LOW at reset, this pin operates as a control to write or read the programmable flag offsets. $\overline{\text{WEN1}}$ must be LOW and WEN2 must be HIGH to write data into the FIFO. Data will not be written into the FIFO if the $\overline{\text{FF}}$ is LOW. If the FIFO is configured to have programmable flags, WEN2/$\overline{\text{LD}}$ is held LOW to write or read the programmable flag offsets.
	Load	I	
$\overline{\text{REN1}}$, $\overline{\text{REN2}}$	Read Enable Inputs	I	Enables the device for Read operation.
WCLK	Write Clock	I	The rising edge clocks data into the FIFO when $\overline{\text{WEN1}}$ is LOW and WEN2/$\overline{\text{LD}}$ is HIGH and the FIFO is not Full. When $\overline{\text{LD}}$ is asserted, WCLK writes data into the programmable flag-off-set register.
RCLK	Read Clock	I	The rising edge clocks data out of the FIFO when $\overline{\text{REN1}}$ and $\overline{\text{REN2}}$ are LOW and the FIFO is not Empty. When WEN2/$\overline{\text{LD}}$ is LOW, RCLK reads data out of the programmable flag-offset register.
$\overline{\text{EF}}$	Empty Flag	O	When $\overline{\text{EF}}$ is LOW, the FIFO is empty. $\overline{\text{EF}}$ is synchronized to RCLK.
$\overline{\text{FF}}$	Full Flag	O	When $\overline{\text{FF}}$ is LOW, the FIFO is full. $\overline{\text{FF}}$ is synchronized to WCLK.
$\overline{\text{PAE}}$	Programmable Almost Empty	O	When $\overline{\text{PAE}}$ is LOW, the FIFO is almost empty based on the almost empty offset value programmed into the FIFO.
$\overline{\text{PAF}}$	Programmable Almost Full	O	When $\overline{\text{PAF}}$ is LOW, the FIFO is almost full based on the almost full offset value programmed into the FIFO.
$\overline{\text{RS}}$	Reset	I	Resets device to empty condition. A reset is required before an initial read or write operation after power-up.
$\overline{\text{OE}}$	Output Enable	I	When $\overline{\text{OE}}$ is LOW, the FIFO's data outputs drive the bus to which they are connected. If $\overline{\text{OE}}$ is HIGH, the FIFO's outputs are in High Z (high-impedance) state.

Electrical Characteristics Over the Operating Range[2]

Parameter	Description	Test Conditions		7C42X1-10 Min.	7C42X1-10 Max.	7C42X1-15 Min.	7C42X1-15 Max.	7C42X1-25 Min.	7C42X1-25 Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = −2.0 mA		2.4		2.4		2.4		V
V_{OL}	Output LOW Voltage	V_{CC} = Min., I_{OL} = 8.0 mA			0.4		0.4		0.4	V
V_{IH}	Input HIGH Voltage			2.2	V_{CC}	2.2	V_{CC}	2.2	V_{CC}	V
V_{IL}	Input LOW Voltage			−3.0	0.8	−3.0	0.8	−3.0	0.8	V
I_{IX}	Input Leakage Current	V_{CC} = Max.		−10	+10	−10	+10	−10	+10	mA
I_{OS}[3]	Output Short Circuit Current	V_{CC} = Max., V_{OUT} = GND		−90		−90		−90		mA
I_{OZL} I_{OZH}	Output OFF, High Z Current	$\overline{OE} \geq V_{IH}$, $V_{SS} < V_O < V_{CC}$		−10	+10	−10	+10	−10	+10	mA
I_{CC1}[4]	Active Power Supply Current	Com'l		35		35		35	mA
		Ind		40		40		40	mA
I_{CC2}[5]	Average Standby Current	Com'l		10		10		10	mA
		Ind		15		15		15	mA

Capacitance[6]

Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input Capacitance	T_A = 25°C, f = 1 MHz, V_{CC} = 5.0V	5	pF
C_{OUT}	Output Capacitance		7	pF

AC Test Loads and Waveforms[7, 8]

R1 1.1 KΩ
5V
OUTPUT
C_L
R2 680Ω
INCLUDING JIG AND SCOPE
42X1–4

ALL INPUT PULSES
3.0V
90%
90%
GND
10%
10%
≤ 3 ns
≤ 3 ns
42X1–5

Equivalent to: THÉVENIN EQUIVALENT
420Ω
OUTPUT ⊶—WW—⊶ 1.91V
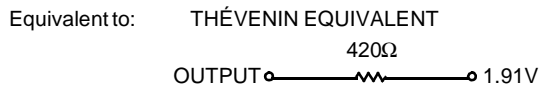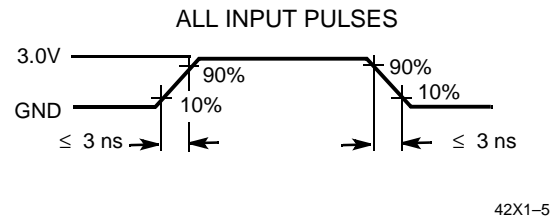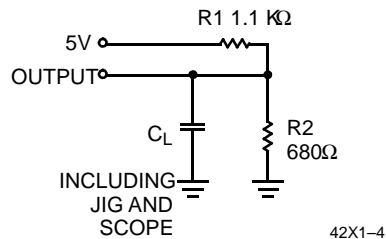
Notes:
2. See the last page of this specification for Group A subgroup testing information.
3. Test no more than one output at a time for not more than one second.
4. Outputs open. Tested at Frequency = 20 MHz.
5. All inputs = V_{CC} − 0.2V, except WCLK and RCLK, which are switching at 20 MHz.
6. Tested initially and after any design or process changes that may affect these parameters.
7. C_L = 30 pF for all AC parameters except for t_{OHZ}.
8. C_L = 5 pF for t_{OHZ}.

Switching Characteristics Over the Operating Range

Parameter	Description	7C42X1-10		7C42X1-15		7C42X1-25		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
t_S	Clock Cycle Frequency		100		66.7		40	MHz
t_A	Data Access Time	2	8	2	10	2	15	ns
t_{CLK}	Clock Cycle Time	10		15		25		ns
t_{CLKH}	Clock HIGH Time	4.5		6		10		ns
t_{CLKL}	Clock LOW Time	4.5		6		10		ns
t_{DS}	Data Set-Up Time	3		4		6		ns
t_{DH}	Data Hold Time	0.5		1		1		ns
t_{ENS}	Enable Set-Up Time	3		4		6		ns
t_{ENH}	Enable Hold Time	0.5		1		1		ns
t_{RS}	Reset Pulse Width[9]	10		15		25		ns
t_{RSS}	Reset Set-Up Time	8		10		15		ns
t_{RSR}	Reset Recovery Time	8		10		15		ns
t_{RSF}	Reset to Flag and Output Time		10		15		25	ns
t_{OLZ}	Output Enable to Output in Low Z[10]	0		0		0		ns
t_{OE}	Output Enable to Output Valid	3	7	3	8	3	12	ns
t_{OHZ}	Output Enable to Output in High Z[10]	3	7	3	8	3	12	ns
t_{WFF}	Write Clock to Full Flag		8		10		15	ns
t_{REF}	Read Clock to Empty Flag		8		10		15	ns
t_{PAF}	Clock to Programmable Almost-Full Flag		8		10		15	ns
t_{PAE}	Clock to Programmable Almost-Full Flag		8		10		15	ns
t_{SKEW1}	Skew Time between Read Clock and Write Clock for Empty Flag and Full Flag	5		6		10		ns
t_{SKEW2}	Skew Time between Read Clock and Write Clock for Almost-Empty Flag and Almost-Full Flag	10		15		18		ns

Notes:
9. Pulse widths less than minimum values are not allowed.
10. Values guaranteed by design, not currently tested.

Switching Waveforms

Write Cycle Timing

42X1–6

Read Cycle Timing

42X1–7
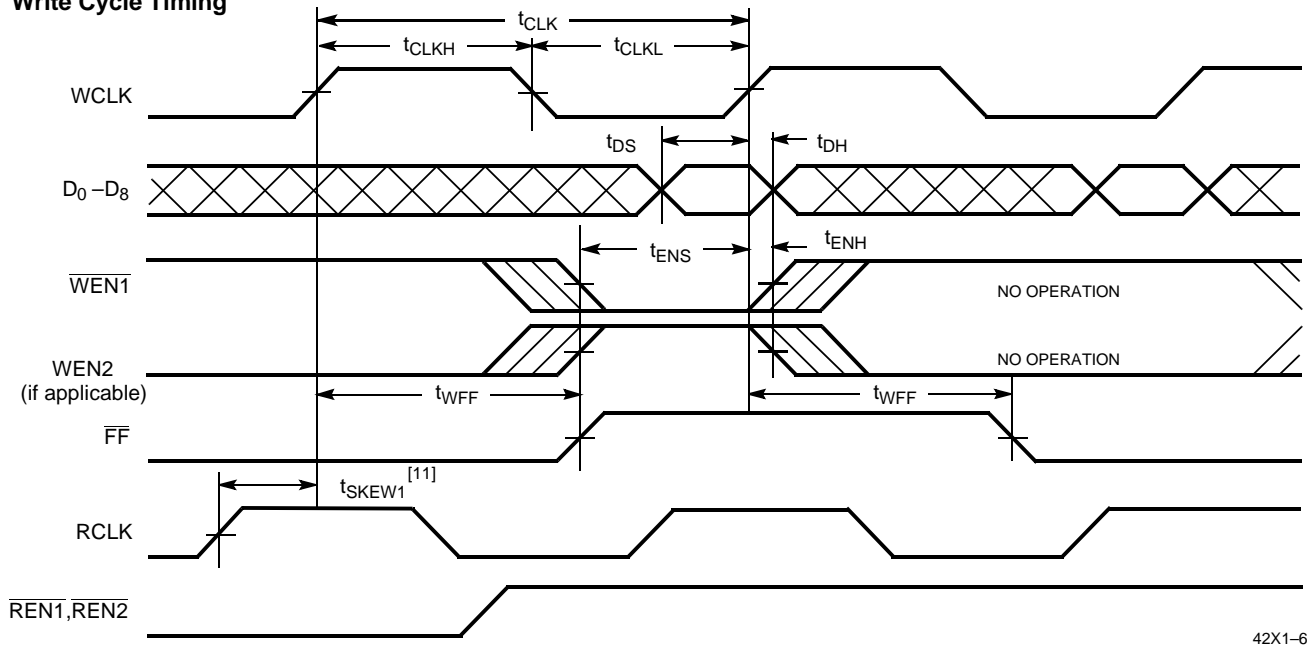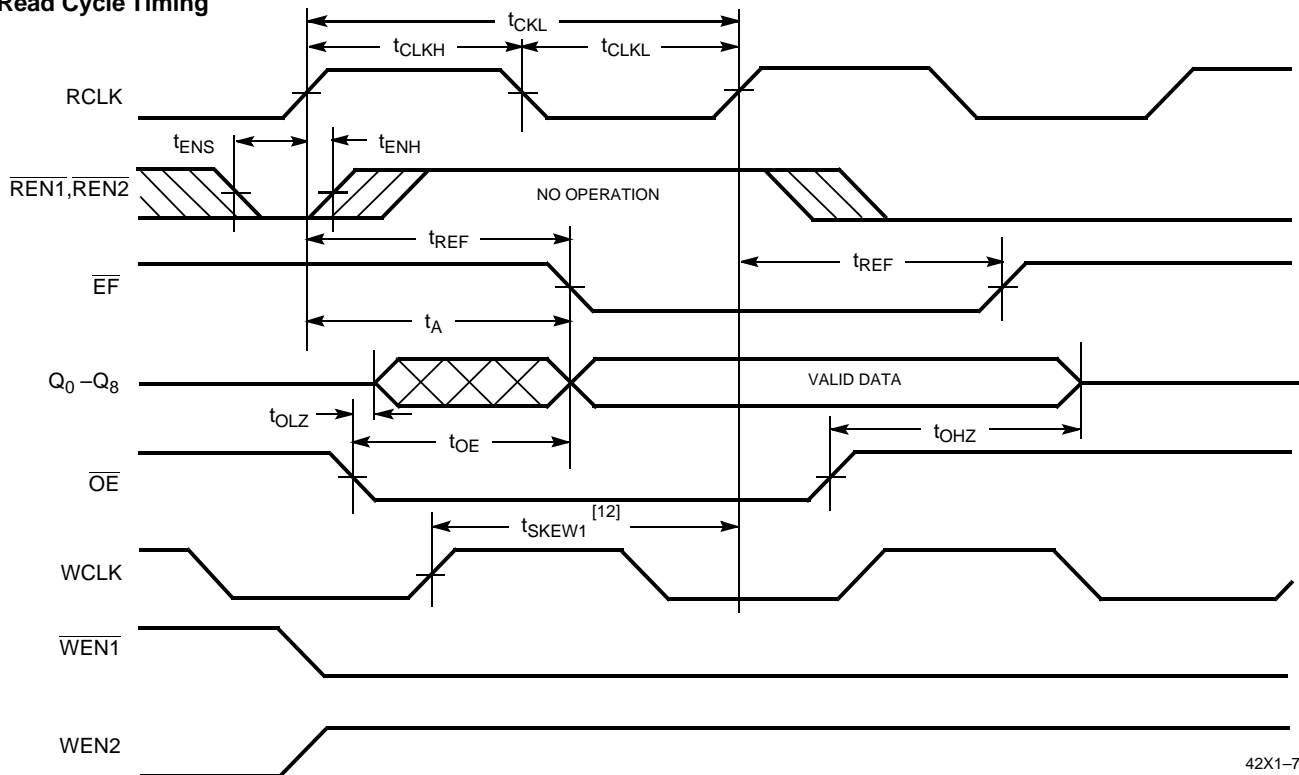
Notes:

11. t_{SKEW1} is the minimum time between a rising RCLK edge and a rising WCLK edge to guarantee that $\overline{FF}$ will go HIGH during the current clock cycle. If the time between the rising edge of RCLK and the rising edge of WCLK is less than t_{SKEW1}, then $\overline{FF}$ may not change state until the next WCLK rising edge.

12. t_{SKEW1} is the minimum time between a rising WCLK edge and a rising RCLK edge to guarantee that $\overline{EF}$ will go HIGH during the current clock cycle. It the time between the rising edge of WCLK and the rising edge of RCLK is less than t_{SKEW1}, then $\overline{EF}$ may not change state until the next RCLK rising edge.

6

Switching Waveforms (continued)

Reset Timing[13]
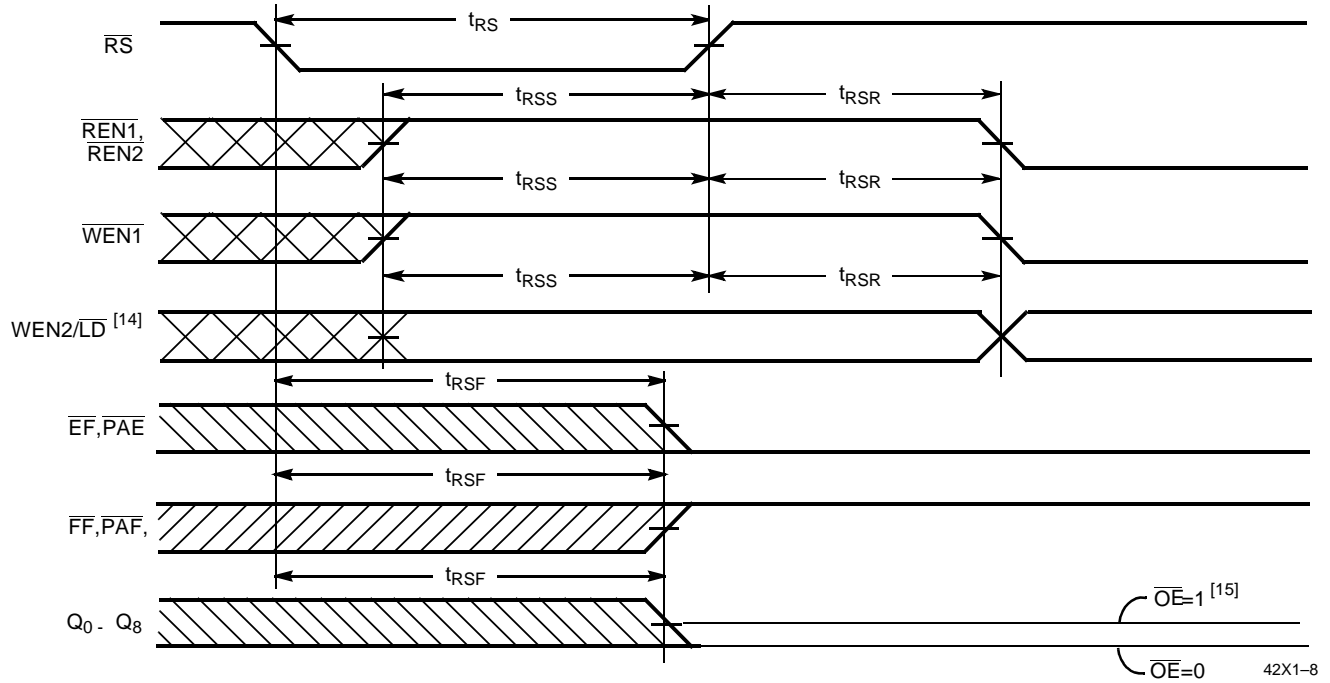
Notes:
13. The clocks (RCLK, WCLK) can be free-running during reset.
14. Holding WEN2/$\overline{LD}$ HIGH during reset will make the pin act as a second enable pin. Holding WEN2/$\overline{LD}$ LOW during reset will make the pin act as a load enable for the programmable flag offset registers.
15. After reset, the outputs will be LOW if $\overline{OE}$ = 0 and three-state if $\overline{OE}$=1.

Switching Waveforms (continued)

First Data Word Latency after Reset with Simultaneous Read and Write
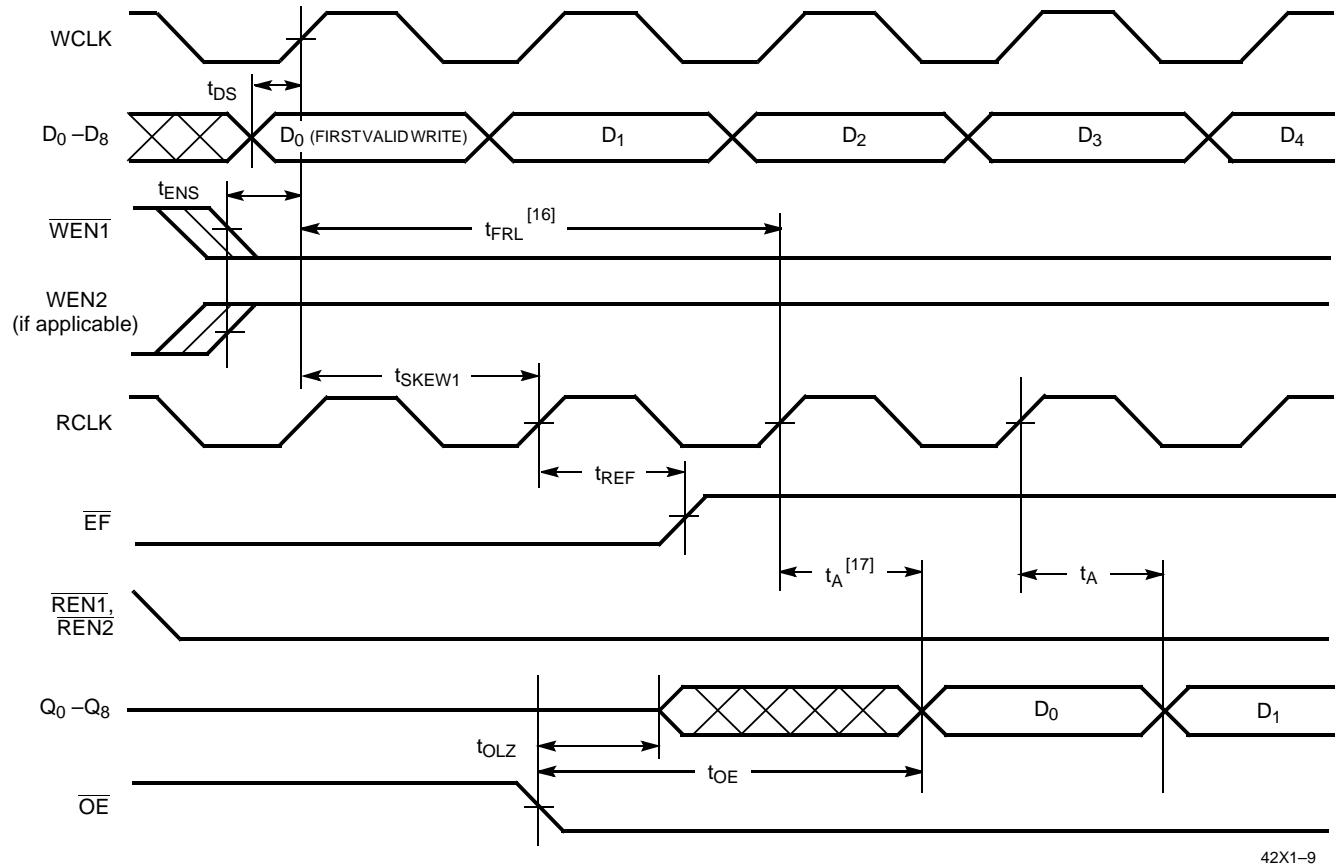
42X1–9

Notes:
16. When $t_{SKEW1} \geq$ minimum specification, t_{FRL} (maximum) = $t_{CLK} + t_{SKEW1}$. When $t_{SKEW1} <$ minimum specification, t_{FRL} (maximum) = either $2^*t_{CLK} + t_{SKEW1}$ or $t_{CLK} + t_{SKEW1}$. The Latency Timing applies only at the Empty Boundary ($\overline{EF}$ = LOW).
17. The first word is available the cycle after $\overline{EF}$ goes HIGH, always.

Switching Waveforms (continued)

Empty Flag Timing
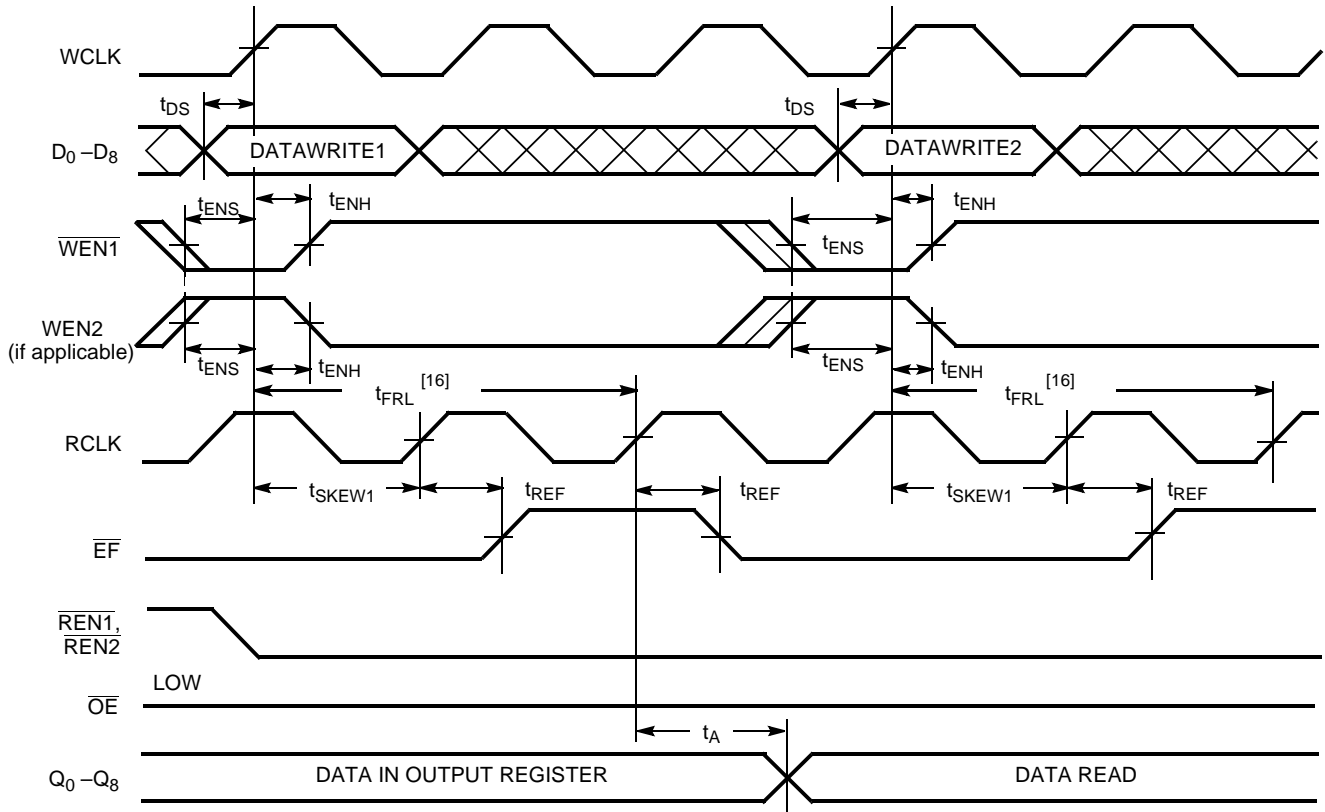
42X1–10

Switching Waveforms (continued)

Full Flag Timing

42X1–11

10
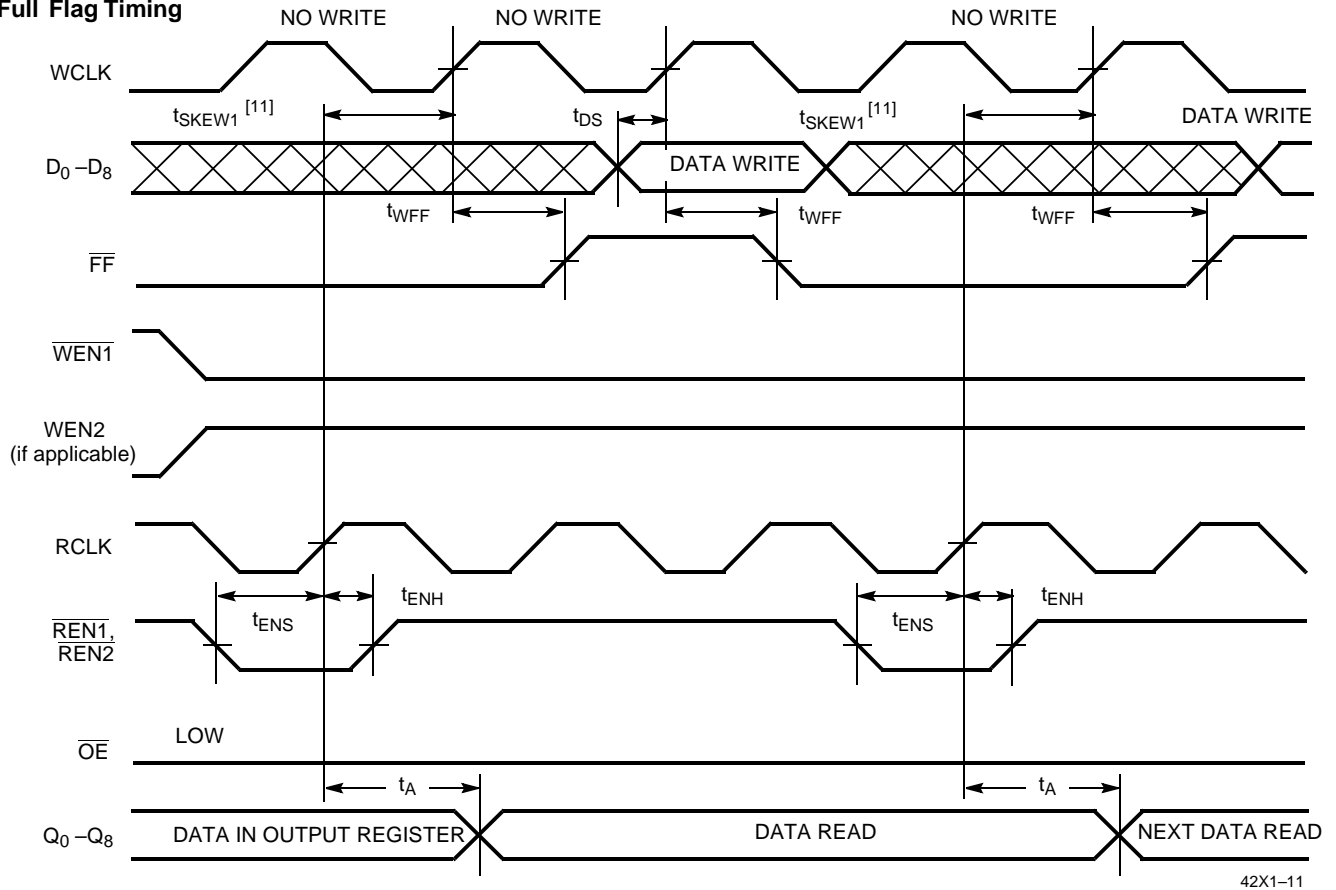
Switching Waveforms (continued)

Programmable Almost Empty Flag Timing

42X1–12
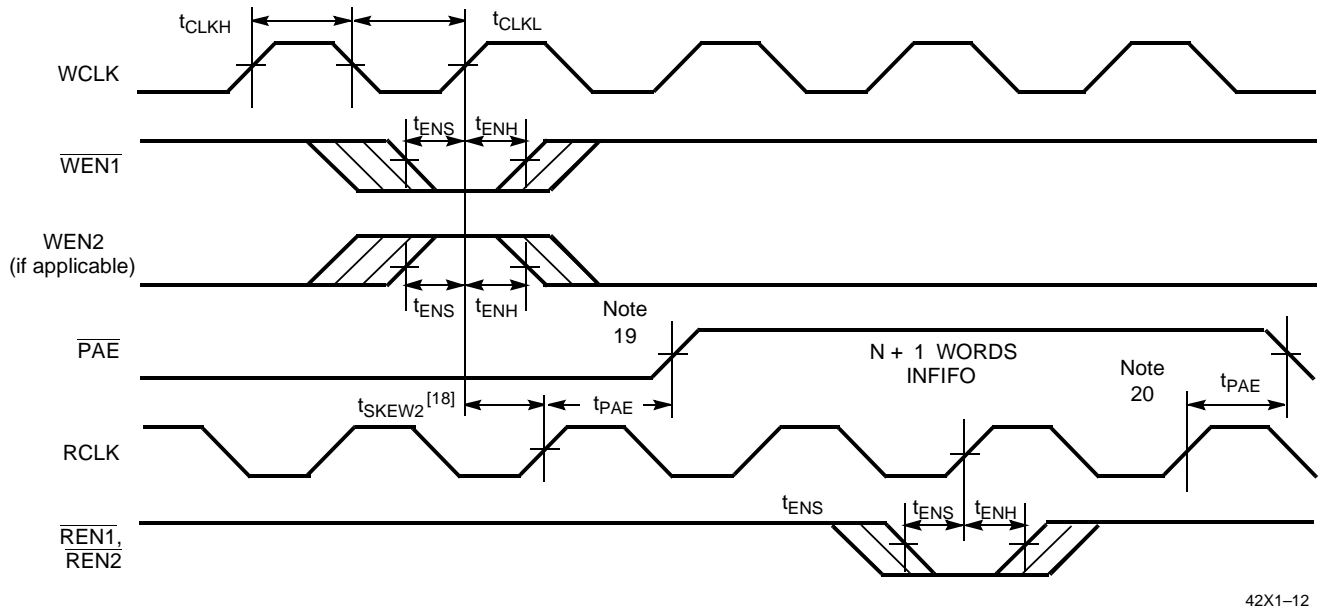
Programmable Almost Full Flag Timing

42X1–13
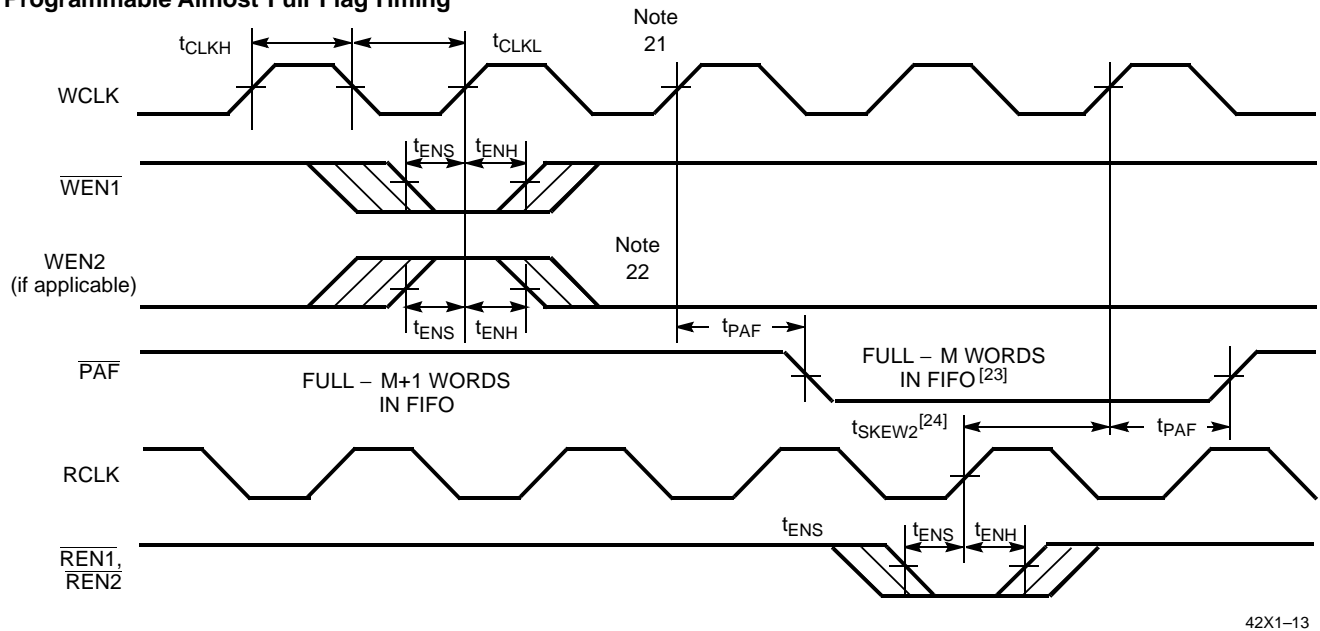
Notes:
18. t$_{SKEW2}$ is the minimum time between a rising WCLK and a rising RCLK edge for $\overline{PAE}$ to change state during that clock cycle. If the time between the edge of WCLK and the rising RCLK is less than t$_{SKEW2}$, then $\overline{PAE}$ may not change state until the next RCLK.
19. PAE offset = n.
20. If a read is performed on this rising edge of the read clock, there will be Empty + (n – 1) words in the FIFO when $\overline{PAE}$ goes LOW.
21. If a write is performed on this rising edge of the write clock, there will be Full – (m – 1) words of the FIFO when $\overline{PAF}$ goes LOW.
22. PAF offset = m.
23. 64-m words for CY7C4421, 256 – m words in FIFO for CY7C4201, 512 – m words for CY7C4211, 1024 – m words for CY7C4221, 2048 – m words for CY7C4231, 4096 – m words for CY7C4241, 8192 – m words for CY7C4251.
24. t$_{SKEW2}$ is the minimum time between a rising RCLK edge and a rising WCLK edge for $\overline{PAF}$ to change during that clock cycle. If the time between the rising edge of RCLK and the rising edge of WCLK is less than t$_{SKEW2}$, then $\overline{PAF}$ may not change state until the next WCLK.

Switching Waveforms (continued)

Write Programmable Registers

42X1–14
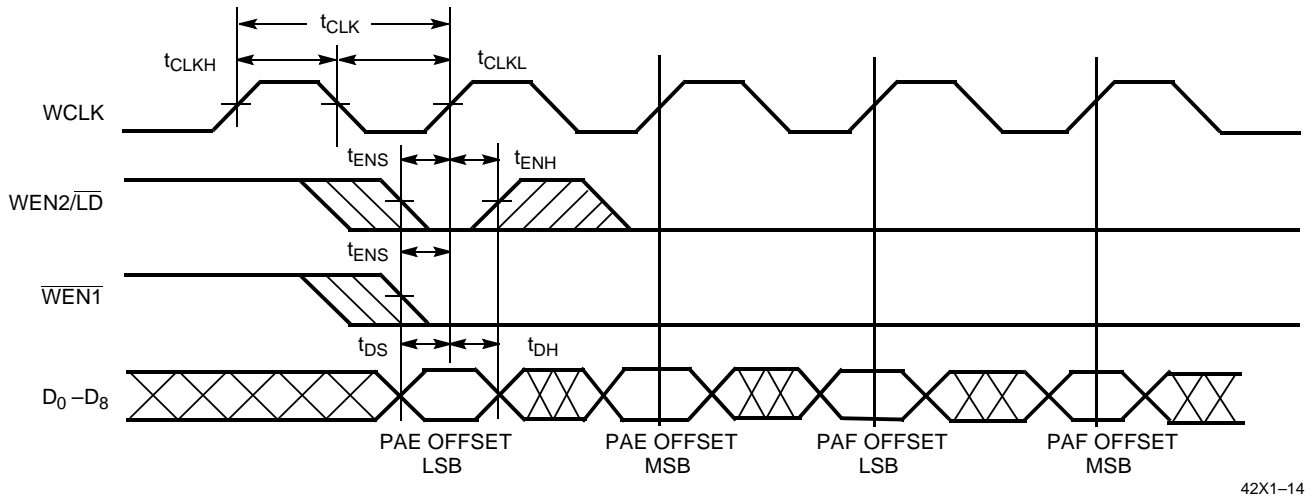
Read Programmable Registers

42X1–15
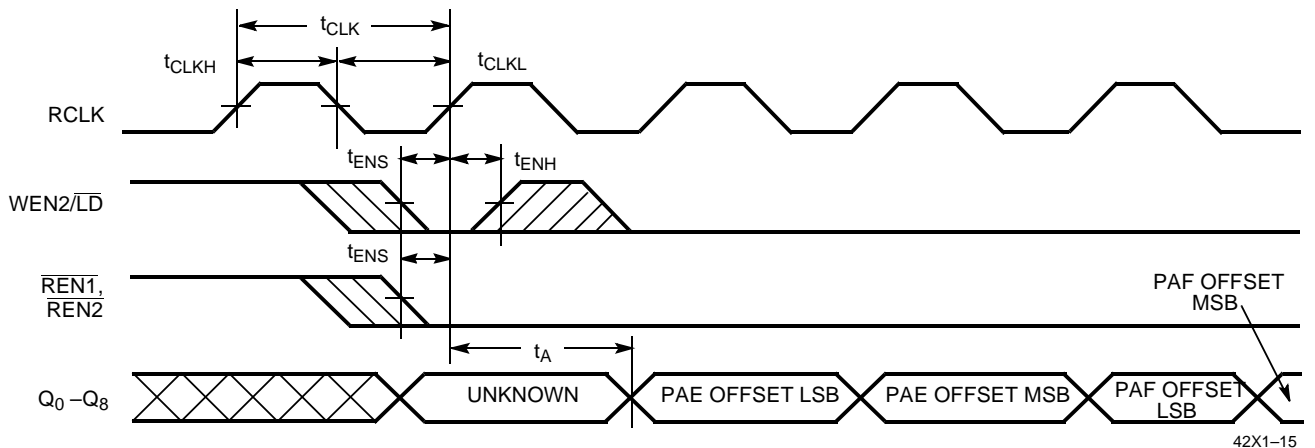
Architecture

The CY7C42X1 consists of an array of 64 to 8K words of 9 bits each (implemented by a dual-port array of SRAM cells), a read pointer, a write pointer, control signals (RCLK, WCLK, $\overline{REN1}$, $\overline{REN2}$, $\overline{WEN1}$, WEN2, $\overline{RS}$), and flags ($\overline{EF}$, $\overline{PAE}$, $\overline{PAF}$, $\overline{FF}$).

Resetting the FIFO

Upon power-up, the FIFO must be reset with a Reset ($\overline{RS}$) cycle. This causes the FIFO to enter the Empty condition signified by $\overline{EF}$ being LOW. All data outputs (Q_{0-8}) go LOW t_{RSF} after the rising edge of $\overline{RS}$. In order for the FIFO to reset to its default state, a falling edge must occur on $\overline{RS}$ and the user must not read or write while $\overline{RS}$ is LOW. All flags are guaranteed to be valid t_{RSF} after $\overline{RS}$ is taken LOW.

FIFO Operation

When the $\overline{WEN1}$ signal is active LOW and WEN2 is active HIGH, data present on the D_{0-8} pins is written into the FIFO on each rising edge of the WCLK signal. Similarly, when the $\overline{REN1}$ and $\overline{REN2}$ signals are active LOW, data in the FIFO memory will be presented on the Q_{0-8} outputs. New data will be presented on each rising edge of RCLK while $\overline{REN1}$ and $\overline{REN2}$ are active. $\overline{REN1}$ and $\overline{REN2}$ must set up t_{ENS} before RCLK for it to be a valid read function. $\overline{WEN1}$ and WEN2 must occur t_{ENS} before WCLK for it to be a valid write function.

An output enable ($\overline{OE}$) pin is provided to three-state the Q_{0-8} outputs when $\overline{OE}$ is asserted. When $\overline{OE}$ is enabled (LOW), data in the output register will be available to the Q_{0-8} outputs after t_{OE}.

The FIFO contains overflow circuitry to disallow additional writes when the FIFO is full, and underflow circuitry to disallow additional reads when the FIFO is empty. An empty FIFO maintains the data of the last valid read on its Q_{0-8} outputs even after additional reads occur.

Write Enable 1 ($\overline{WEN1}$) - If the FIFO is configured for programmable flags, Write Enable 1 ($\overline{WEN1}$) is the only write enable control pin. In this configuration, when Write Enable 1

($\overline{WEN1}$) is LOW, data can be loaded into the input register and RAM array on the LOW-to-HIGH transition of every write clock (WCLK). Data is stored is the RAM array sequentially and independently of any on-going read operation.

Write Enable 2/Load (WEN2/$\overline{LD}$) - This is a dual-purpose pin. The FIFO is configured at Reset to have programmable flags or to have two write enables, which allows for depth expansion. If Write Enable 2/Load (WEN2/$\overline{LD}$) is set active HIGH at Reset ($\overline{RS}$=LOW), this pin operates as a second write enable pin.

If the FIFO is configured to have two write enables, when Write Enable ($\overline{WEN1}$) is LOW and Write Enable 2/Load (WEN2/$\overline{LD}$) is HIGH, data can be loaded into the input register and RAM array on the LOW-to-HIGH transition of every write clock (WCLK). Data is stored in the RAM array sequentially and independently of any on-going read operation.

Programming

When WEN2/$\overline{LD}$ is held LOW during Reset, this pin is the load ($\overline{LD}$) enable for flag offset programming. In this configuration, WEN2/$\overline{LD}$ can be used to access the four 8-bit offset registers contained in the CY7C42X1 for writing or reading data to these registers.

When the device is configured for programmable flags and both WEN2/$\overline{LD}$ and $\overline{WEN1}$ are LOW, the first LOW-to-HIGH transition of WCLK writes data from the data inputs to the empty offset least significant bit (LSB) register. The second, third, and fourth LOW-to-HIGH transitions of WCLK store data in the empty offset most significant bit (MSB) register, full offset LSB register, and full offset MSB register, respectively, when WEN2/$\overline{LD}$ and $\overline{WEN1}$ are LOW. The fifth LOW-to-HIGH transition of WCLK while WEN2/$\overline{LD}$ and $\overline{WEN1}$ are LOW writes data to the empty LSB register again. *Figure 1* shows the registers sizes and default values for the various device types.

It is not necessary to write to all the offset registers at one time. A subset of the offset registers can be written; then by bringing the WEN2/$\overline{LD}$ input HIGH, the FIFO is returned to normal read and write operation. The next time WEN2/$\overline{LD}$ is brought LOW, a write operation stores data in the next offset register in sequence.

The contents of the offset registers can be read to the data outputs when WEN2/$\overline{LD}$ is LOW and both $\overline{REN1}$ and $\overline{REN2}$ are LOW. LOW-to-HIGH transitions of RCLK read register contents to the data outputs. Writes and reads should not be preformed simultaneously on the offset registers.
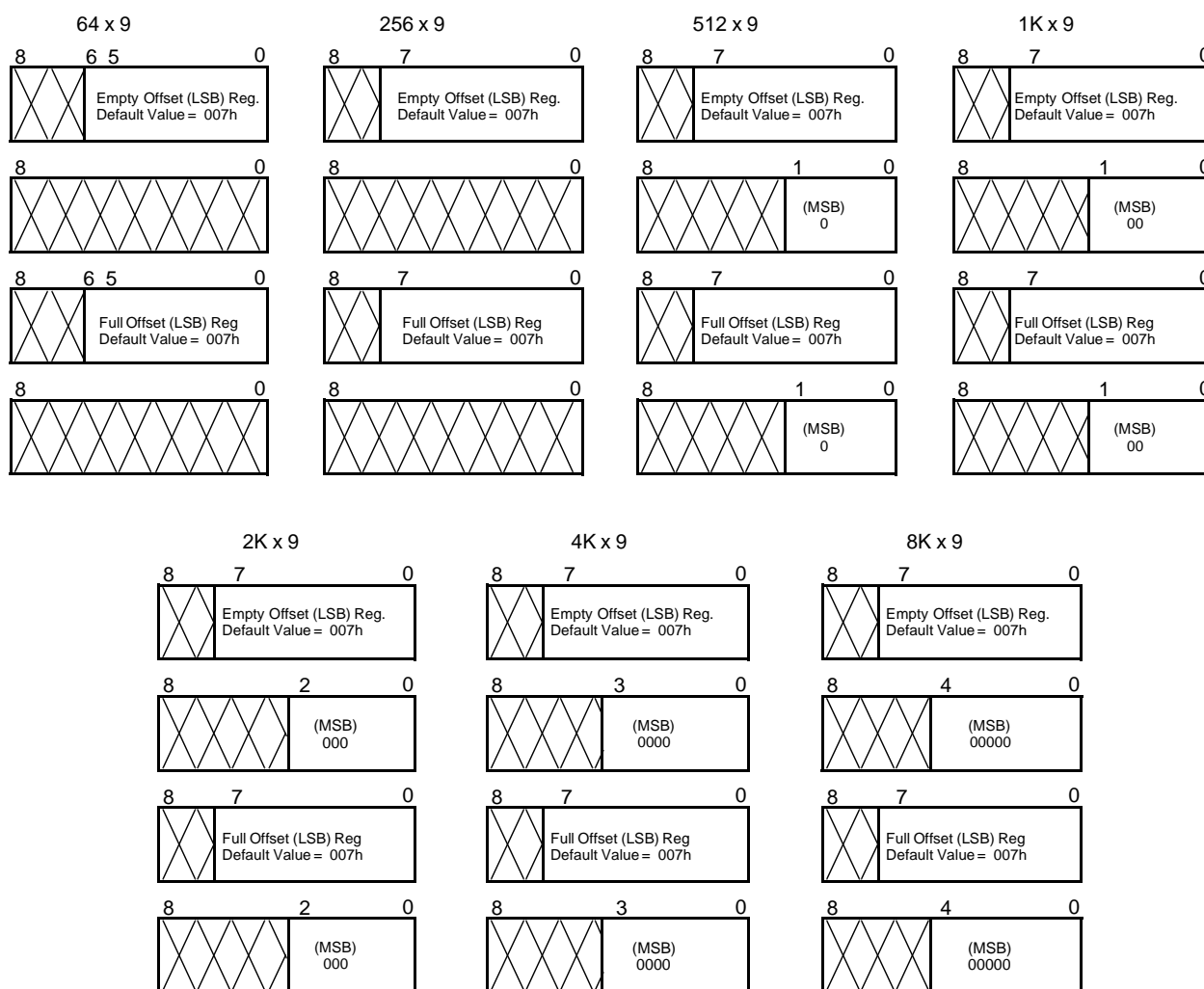

Figure 1. Offset Register Location and Default Values

Width Expansion Configuration

Word width may be increased simply by connecting the corresponding input controls signals of multiple devices. A composite flag should be created for each of the end-point status flags ($\overline{EF}$ and $\overline{FF}$). The partial status flags ($\overline{PAE}$ and $\overline{PAF}$) can be detected from any one device. *Figure 2* demonstrates a 18-bit word width by using two CY7C42X1s. Any word width can be attained by adding additional CY7C42X1s.

When the CY7C42X1 is in a Width Expansion Configuration, the Read Enable ($\overline{REN2}$) control input can be grounded (See *Figure 2*). In this configuration, the Write Enable 2/Load (WEN2/$\overline{LD}$) pin is set to LOW at Reset so that the pin operates as a control to load and read the programmable flag offsets.

Flag Operation

The CY7C42X1 devices provide four flag pins to indicate the condition of the FIFO contents. Empty, Full, $\overline{PAE}$, and $\overline{PAF}$ are synchronous.

Full Flag

The Full Flag ($\overline{FF}$) will go LOW when device is full. Write operations are inhibited whenever $\overline{FF}$ is LOW regardless of the state of $\overline{WEN1}$ and WEN2/$\overline{LD}$. $\overline{FF}$ is synchronized to WCLK, i.e., it is exclusively updated by each rising edge of WCLK.

Empty Flag

The Empty Flag ($\overline{EF}$) will go LOW when the device is empty. Read operations are inhibited whenever $\overline{EF}$ is LOW, regardless of the state of $\overline{REN1}$ and $\overline{REN2}$. $\overline{EF}$ is synchronized to RCLK, i.e., it is exclusively updated by each rising edge of RCLK.

42X1–16

Figure 2. Block Diagram of 64 x 9,256 x 9,512 x 9,1024 x 9,2048 x 9,4096 x 9,8192 x 9 Synchronous FIFO Memory Used in a Width Expansion Configuration

Typical AC and DC Characteristics

NORMALIZED SUPPLY CURRENT vs. SUPPLY VOLTAGE

$V_{IN} = 3.0V$
$T_A = 25°C$
$f = 100$ MHz
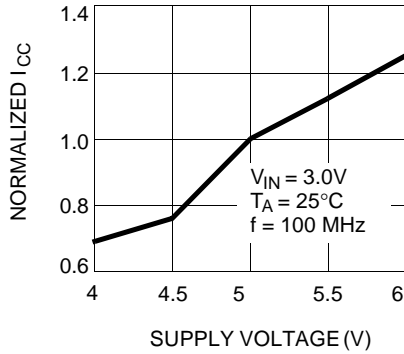
NORMALIZED SUPPLY CURRENT vs. AMBIENT TEMPERATURE

$V_{IN} = 3.0V$
$V_{CC} = 5.0V$
$f = 100$ MHz
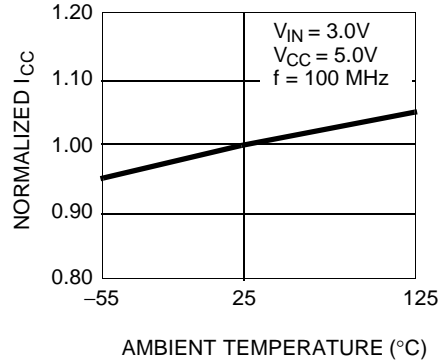
NORMALIZED SUPPLY CURRENT vs. FREQUENCY

$V_{CC} = 5.0V$
$T_A = 25°C$
$V_{IN} = 3.0V$
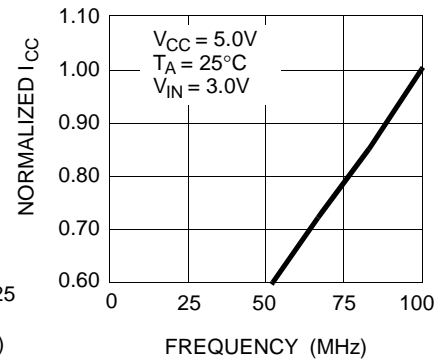
NORMALIZED t_A vs. SUPPLY VOLTAGE
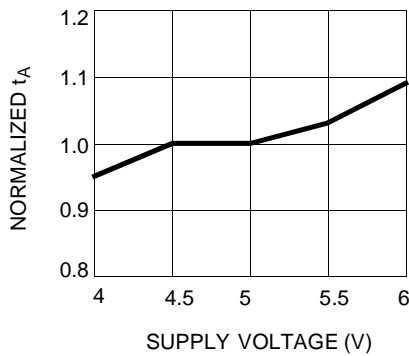
NORMALIZED t_A vs. AMBIENT TEMPERATURE

$V_{CC} = 5.0V$
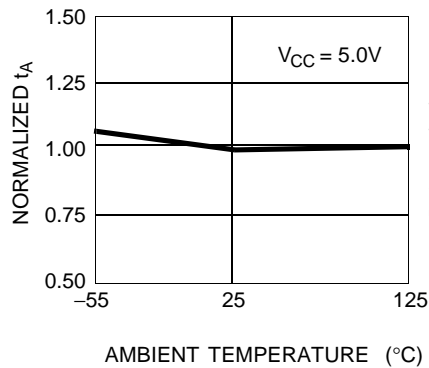
TYPICAL t_A CHANGE vs. OUTPUT LOADING

$V_{CC} = 5.0V$
$T_A = 25°C$
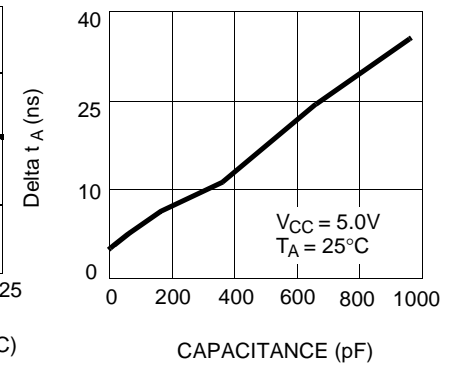
OUTPUT SOURCE CURRENT vs. OUTPUT VOLTAGE
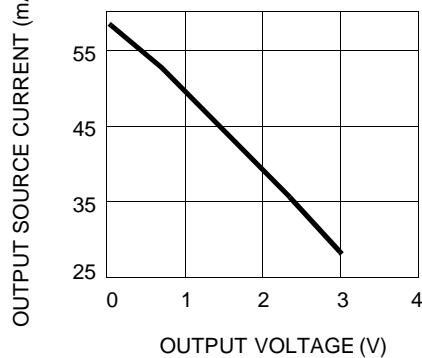
OUTPUT SINK CURRENT vs. OUTPUT VOLTAGE

16
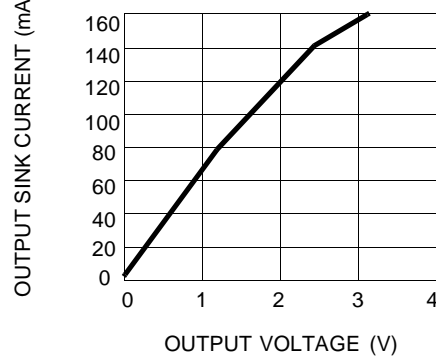
Ordering Information

64 x 9 Synchronous FIFO

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C4421-10AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4421-10JC	J65	32-Lead Plastic Leaded Chip Carrier	
15	CY7C4421-15AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4421-15JC	J65	32-Lead Plastic Leaded Chip Carrier	

256 x 9 Synchronous FIFO

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C4201-10AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4201-10JC	J65	32-Lead Plastic Leaded Chip Carrier	
15	CY7C4201-15AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4201-15JC	J65	32-Lead Plastic Leaded Chip Carrier	
25	CY7C4201-25AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4201-25JC	J65	32-Lead Plastic Leaded Chip Carrier	
	CY7C4201-25AI	A32	32-Lead Thin Quad Flatpack	Industrial

512 x 9 Synchronous FIFO

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C4211-10AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4211-10JC	J65	32-Lead Plastic Leaded Chip Carrier	
	CY7C4211-10AI	A32	32-Lead Thin Quad Flatpack	Industrial
	CY7C4211-10JI	J65	32-Lead Plastic Leaded Chip Carrier	
15	CY7C4211-15AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4211-15JC	J65	32-Lead Plastic Leaded Chip Carrier	
	CY7C4211-15AI	A32	32-Lead Thin Quad Flatpack	Industrial
25	CY7C4211-25AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4211-25JC	J65	32-Lead Plastic Leaded Chip Carrier	

1K x 9 Synchronous FIFO

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C4221-10AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4221-10JC	J65	32-Lead Plastic Leaded Chip Carrier	
15	CY7C4221-15AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4221-15JC	J65	32-Lead Plastic Leaded Chip Carrier	
25	CY7C4221-25AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4221-25JC	J65	32-Lead Plastic Leaded Chip Carrier	

Ordering Information (Continued)

2K x 9 Synchronous FIFO

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C4231-10AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4231-10JC	J65	32-Lead Plastic Leaded Chip Carrier	
15	CY7C4231-15AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4231-15JC	J65	32-Lead Plastic Leaded Chip Carrier	
25	CY7C4231-25AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4231-25JC	J65	32-Lead Plastic Leaded Chip Carrier	

4K x 9 Synchronous FIFO

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C4241-10AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4241-10JC	J65	32-Lead Plastic Leaded Chip Carrier	
	CY7C4241-10JI	J65	32-Lead Plastic Leaded Chip Carrier	Industrial
15	CY7C4241-15AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4241-15JC	J65	32-Lead Plastic Leaded Chip Carrier	
25	CY7C4241-25AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4241-25JC	J65	32-Lead Plastic Leaded Chip Carrier	
	CY7C4241-25JI	J65	32-Lead Plastic Leaded Chip Carrier	Industrial

8K x 9 Synchronous FIFO

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C4251-10AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4251-10JC	J65	32-Lead Plastic Leaded Chip Carrier	
	CY7C4251-10AI	A32	32-Lead Thin Quad Flatpack	Industrial
15	CY7C4251-15AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4251-15JC	J65	32-Lead Plastic Leaded Chip Carrier	
25	CY7C4251-25AC	A32	32-Lead Thin Quad Flatpack	Commercial
	CY7C4251-25JC	J65	32-Lead Plastic Leaded Chip Carrier	
	CY7C4251-25AI	A32	32-Lead Thin Quad Flatpack	Industrial

Document #: 38-00419-*B

Package Diagrams

32-Lead Thin Plastic Quad Flatpack 7 x 7 x 1.0 mm A32

DIMENSIONS ARE IN MILLIMETERS

DETAIL A

51-85063-B

32-Lead Plastic Leaded Chip Carrier J65

DIMENSIONS IN INCHES MIN.
                      MAX.